

N-Channel Enhancement Mode Field Effect Transistor

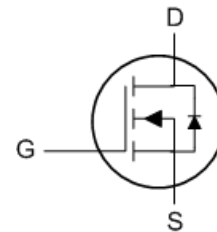
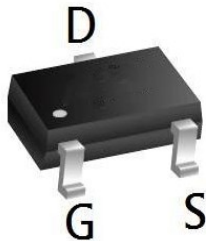
- $V_{DS} = 30V, I_D = 7.0A$
- $R_{DS(ON)} = 12m\Omega @ V_{GS}=10V$
- $R_{DS(ON)} = 17m\Omega @ V_{GS}=4.5V$

Description

The SI017N03T is the high cell density trenched N-ch MOSFETs, which provides excellent $R_{DS(ON)}$ and efficiency for most of the small power switching and load switch applications.

The SI017N03T meet the RoHS and Green Product requirement with full function reliability approved.

- ★ Green Device Available
- ★ Super Low Gate Charge
- ★ Excellent $C_{dv/dt}$ effect decline
- ★ Advanced high cell density Trench technology



Absolute Maximum Ratings

| Symbol | Parameter | Rating | Units |
|------------------------|--|------------|------------|
| V_{DS} | Drain-Source Voltage | 30 | V |
| V_{GS} | Gate-Source Voltage | ± 20 | V |
| $I_D @ T_A=25^\circ C$ | Continuous Drain Current, $V_{GS} @ 10V^1$ | 7.0 | A |
| $I_D @ T_A=70^\circ C$ | Continuous Drain Current, $V_{GS} @ 10V^1$ | 5.5 | A |
| I_{DM} | Pulsed Drain Current ² | 29.4 | A |
| $P_D @ T_A=25^\circ C$ | Total Power Dissipation ³ | 2.0 | W |
| T_{STG} | Storage Temperature Range | -55 to 150 | $^\circ C$ |
| T_J | Operating Junction Temperature Range | -55 to 150 | $^\circ C$ |

Thermal Data

| Symbol | Parameter | Typ. | Max. | Unit |
|-----------------|--|------|------|--------------|
| $R_{\theta JA}$ | Thermal Resistance Junction-ambient ¹ | --- | 85 | $^\circ C/W$ |
| $R_{\theta JC}$ | Thermal Resistance Junction-Case ¹ | --- | --- | $^\circ C/W$ |

Electrical Characteristics ($T_J=25\text{ }^\circ\text{C}$, unless otherwise noted)

| Symbol | Parameter | Test Condition | Min. | Typ. | Max. | Units |
|---------------|---|--|------------------|------|-----------|------------|
| $V_{(BR)DSS}$ | Drain-Source Breakdown Voltage | $V_{GS}=0V, I_D=250\mu A$ | 30 | - | - | V |
| I_{DSS} | Zero Gate Voltage Drain Current | $V_{DS}=30V, V_{GS}=0V,$ | - | - | 1.0 | μA |
| I_{GSS} | Gate to Body Leakage Current | $V_{DS}=0V, V_{GS}=\pm 20V$ | - | - | ± 100 | nA |
| $V_{GS(th)}$ | Gate Threshold Voltage | $V_{DS}=V_{GS}, I_D=250\mu A$ | 1.0 | 1.5 | 2.5 | V |
| $R_{DS(on)}$ | Static Drain-Source on-Resistance <small>note3</small> | $V_{GS}=10V, I_D=10A$ | - | 12 | 17 | m Ω |
| | | $V_{GS}=4.5V, I_D=5A$ | - | 17 | 25 | |
| C_{iss} | Input Capacitance | $V_{DS}=15V, V_{GS}=0V,$ $f=1.0MHz$ | - | 614 | - | pF |
| C_{oss} | Output Capacitance | | - | 118 | - | pF |
| C_{rss} | Reverse Transfer Capacitance | | - | 98 | - | pF |
| Q_g | Total Gate Charge | $V_{DS}=15V, I_D=11A,$ $V_{GS}=10V$ | - | 16 | - | nC |
| Q_{gs} | Gate-Source Charge | | - | 2.7 | - | nC |
| Q_{gd} | Gate-Drain("Miller") Charge | | - | 4.5 | - | nC |
| $t_{d(on)}$ | Turn-on Delay Time | $V_{DS}=15V, R_L=1.35\Omega,$ $R_{GEN}=3\Omega, V_{GS}=10V$ | - | 6 | - | ns |
| t_r | Turn-on Rise Time | | - | 10 | - | ns |
| $t_{d(off)}$ | Turn-off Delay Time | | - | 30 | - | ns |
| t_f | Turn-off Fall Time | | - | 6.5 | - | ns |
| I_S | Maximum Continuous Drain to Source Diode Forward Current | | - | - | 7 | A |
| I_{SM} | Maximum Pulsed Drain to Source Diode Forward Current | | - | - | 30 | A |
| V_{SD} | Drain to Source Diode Forward Voltage | $V_{GS}=0V, I_S=15A$ | - | - | 1.2 | V |
| t_{rr} | Body Diode Reverse Recovery Time | $I_F=11A, di/dt=500A/\mu s$ | - | 7 | - | ns |
| Q_{rr} | Body Diode Reverse Recovery Charge | | $T_J=25^\circ C$ | - | 10 | - |

Diode Characteristics

| Symbol | Parameter | Conditions | Min. | Typ. | Max. | Unit |
|----------|--|---|------|------|------|------|
| I_S | Continuous Source Current ^{1,5} | $V_G=V_D=0V$, Force Current | --- | --- | 7 | A |
| V_{SD} | Diode Forward Voltage ² | $V_{GS}=0V, I_S=1A, T_J=25^\circ C$ | --- | --- | 1 | V |
| t_{rr} | Reverse Recovery Time | $I_F=8A, di/dt=100A/\mu s,$ $T_J=25^\circ C$ | --- | 8 | --- | nS |
| Q_{rr} | Reverse Recovery Charge | | --- | 2.9 | --- | nC |

Note :

Figure 1: Output Characteristics

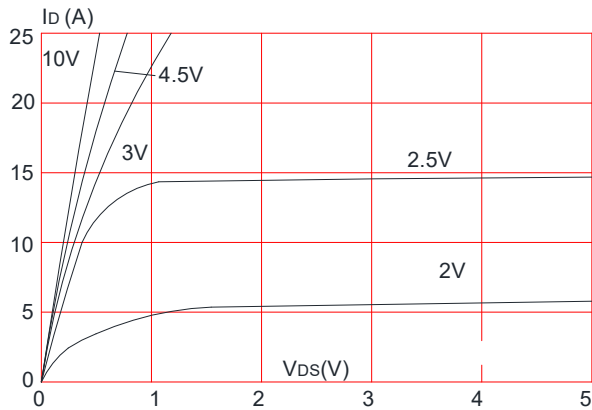


Figure 2: Typical Transfer Characteristics

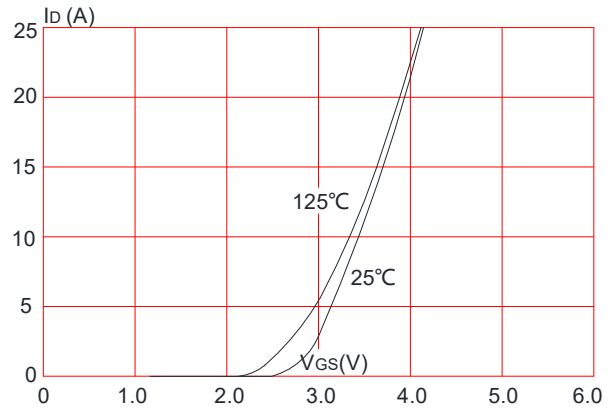


Figure 3: On-resistance vs. Drain Current

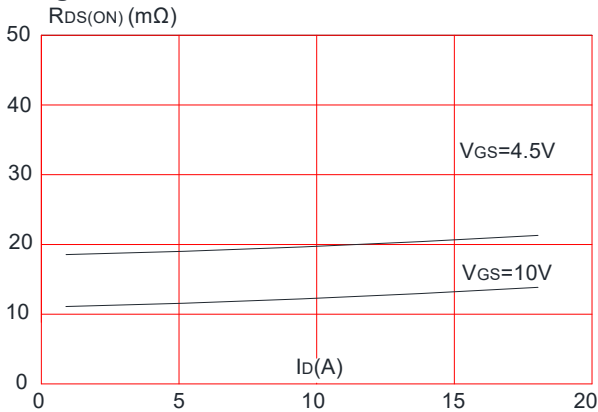


Figure 4: Body Diode Characteristics

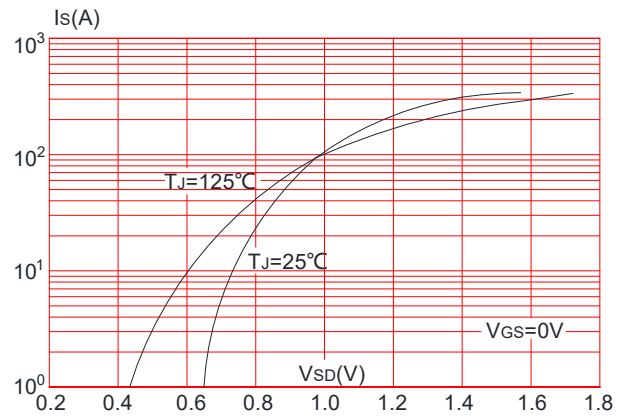


Figure 5: Gate Charge Characteristics

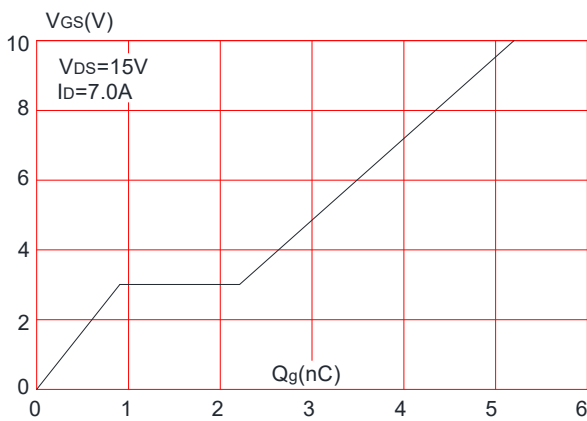


Figure 6: Capacitance Characteristics

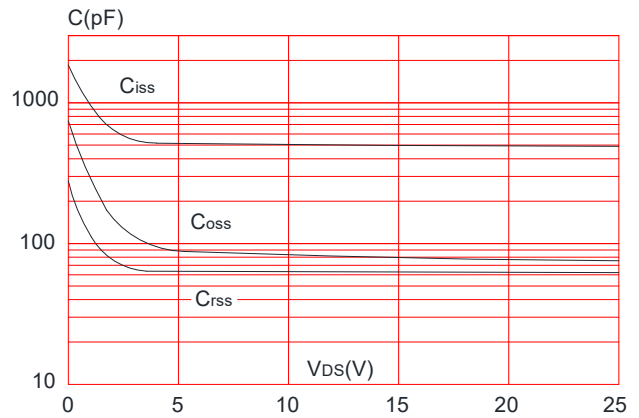


Figure 7: Normalized Breakdown Voltage vs. Junction Temperature

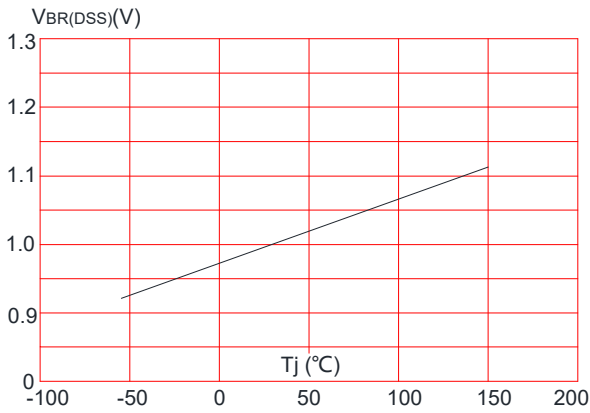


Figure 8: Normalized on Resistance vs. Junction Temperature

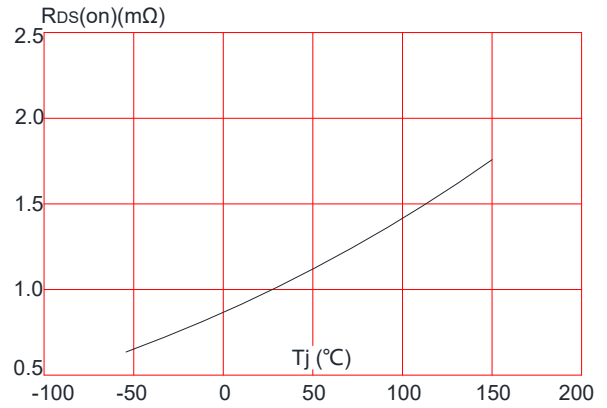


Figure 9: Maximum Safe Operating Area

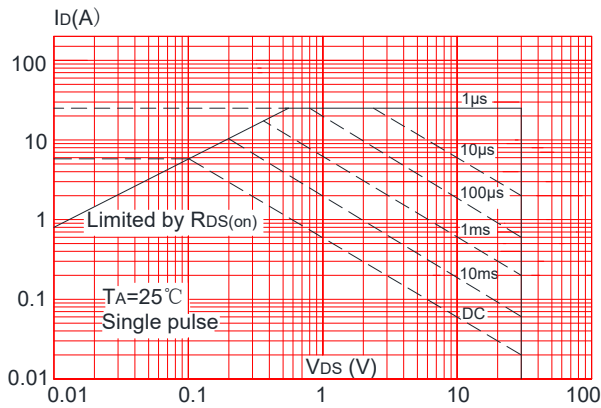


Figure 10: Maximum Continuous Drain Current vs. Ambient Temperature

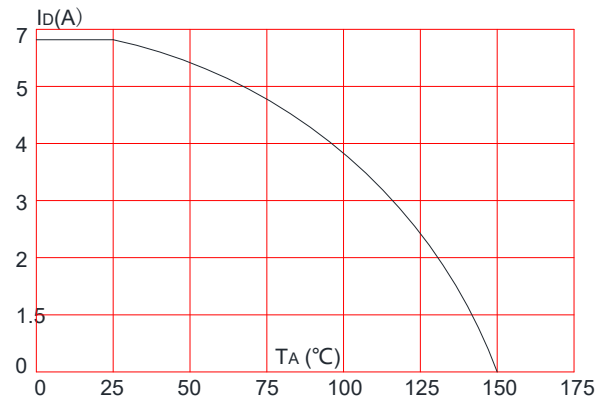
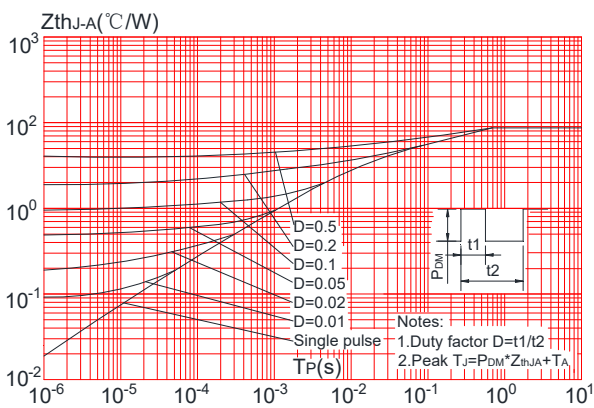
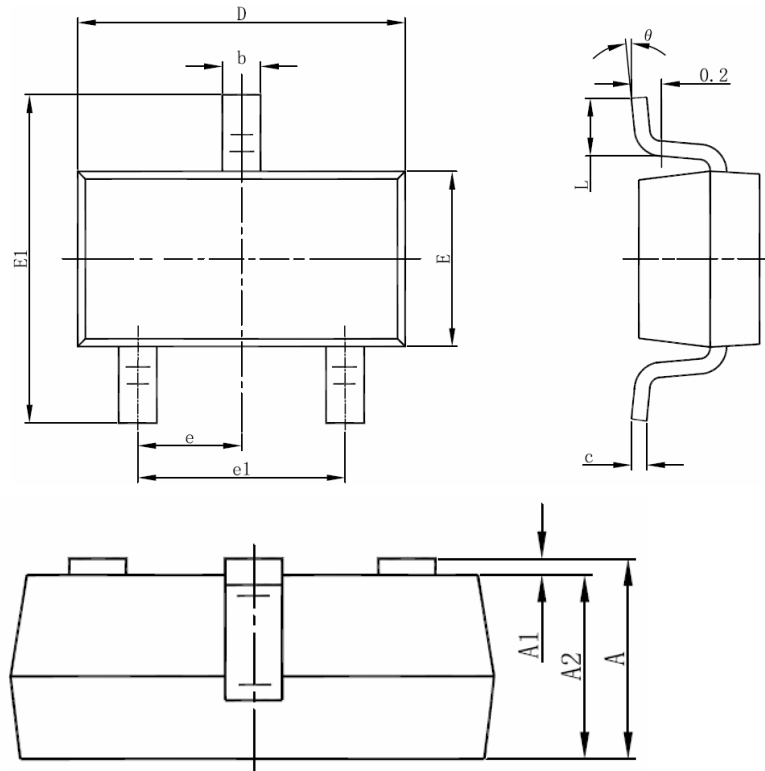


Figure 11: Maximum Effective Transient Thermal Impedance, Junction-to-Ambient



■ SOT-23-3L Package information



| Symbol | Dimensions In Millimeters | | Dimensions In Inches | |
|--------|---------------------------|-------|----------------------|-------|
| | Min | Max | Min | Max |
| A | 1.050 | 1.250 | 0.041 | 0.049 |
| A1 | 0.000 | 0.100 | 0.000 | 0.004 |
| A2 | 1.050 | 1.150 | 0.041 | 0.045 |
| b | 0.300 | 0.500 | 0.012 | 0.020 |
| c | 0.100 | 0.200 | 0.004 | 0.008 |
| D | 2.820 | 3.020 | 0.111 | 0.119 |
| E | 1.500 | 1.700 | 0.059 | 0.067 |
| E1 | 2.650 | 2.950 | 0.104 | 0.116 |
| e | 0.950(BSC) | | 0.037(BSC) | |
| e1 | 1.800 | 2.000 | 0.071 | 0.079 |
| L | 0.300 | 0.600 | 0.012 | 0.024 |
| θ | 0° | 8° | 0° | 8° |